

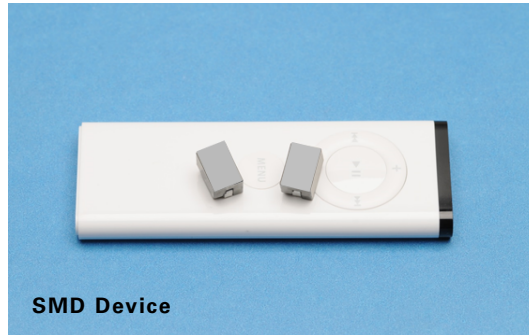


**THE DATASHEET OF
FP1107R1-R15-R**



FP1107

High frequency, high current power inductors



SMD Device

Product features

- 7.2 x 11.0 x 7.5mm surface mount package
- Ferrite core material
- High current carrying capacity, low core losses
- Controlled DCR tolerance for sensing circuits
- Inductance range from 70nH to 510nH
- Current range from 18 amps to 140 amps
- Frequency range up to 2MHz

Applications

- Multi-phase regulators
- Voltage Regulator Module (VRM)
- Desktop and server VRMs and EVRDs
- Data networking and storage systems
- Graphics cards and battery power systems
- Point-of-load modules
- DCR sensing

Environmental data

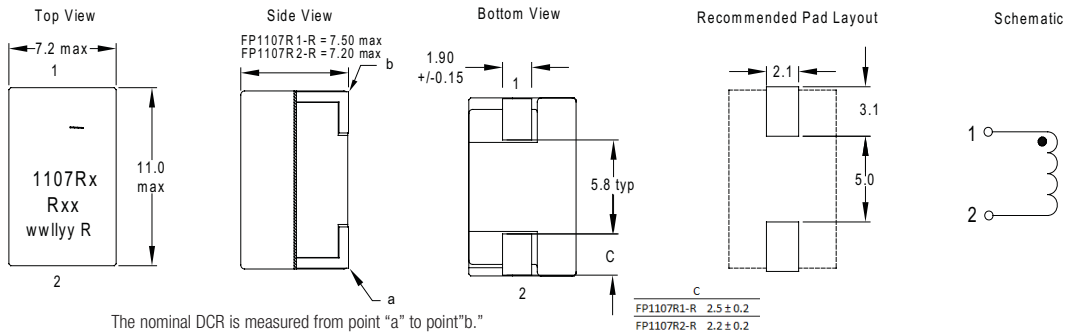
- Storage temperature range (component):
-40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C
(ambient plus self-temperature rise)
- Solder reflow temperature:
J-STD-020 (latest revision) compliant



Product Specifications							
Part Number	OCL ¹ ± 10% (nH)	FLL ² Min. (nH)	I _{rms} ³ (Amps)	I _{sat} ⁴ @ 25°C (Amps)	I _{sat} ⁵ @ 125°C (Amps)	DCR (mΩ) @ 20°C	K-factor ⁶
R1 Version							
FP1107R1-R07-R	70	50	55	140	123	0.29 ± 8%	361.1
FP1107R1-R12-R	120	86		90	72		361.1
FP1107R1-R15-R	150	108		70	56		361.1
FP1107R1-R23-R	230	166		45	36		361.1
FP1107R1-R30-R	300	217		35	28		361.1
FP1107R1-R40-R	400	288		25	20		361.1
FP1107R1-R51-R	510	364		18	14.5		361.1
R2 Version							
FP1107R2-R07-R	70	50	42	140	123	0.47 ± 6.4%	363.3
FP1107R2-R12-R	120	86		90	72		363.3
FP1107R2-R15-R	150	108		70	56		363.3
FP1107R2-R23-R	230	166		45	36		363.3
FP1107R2-R30-R	300	217		35	28		363.3
FP1107R2-R40-R	400	288		25	20		363.3
FP1107R2-R51-R	510	364		18	14.5		363.3

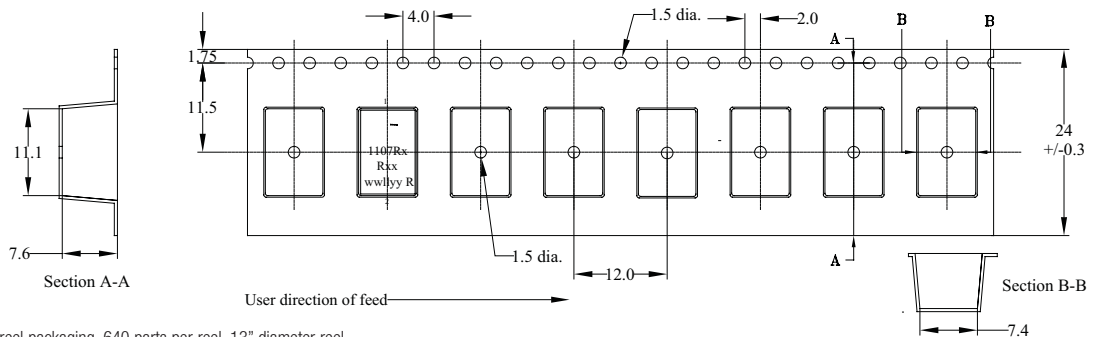
- Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10V_{rms}, 0.0A_{dc}
- Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1V_{rms}, I_{sat}¹
- I_{rms}: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 125°C under worst case operating conditions verified in the end application.
- I_{sat}¹: Peak current for approximately 20% rolloff at +25°C. I_{sat}²:
- Peak current for approximately 20% rolloff at +125°C.
- K-factor: Used to determine B_{pn} for core loss (see graph). B_{pn} = K * L * ΔI * 10⁻³, B_{pn}: (Gauss), K: (K-factor from table), L: (inductance in nH), ΔI (peak-to-peak ripple current in amps).
- Part Number Definition: FP1107Rx-Rxx-R
 - FP1107 = Product code and size
 - Rx = Inductance value in μH, R = decimal point
 - Rx is the DCR indicator
 - "-R" suffix = RoHS compliant

Dimensions- mm

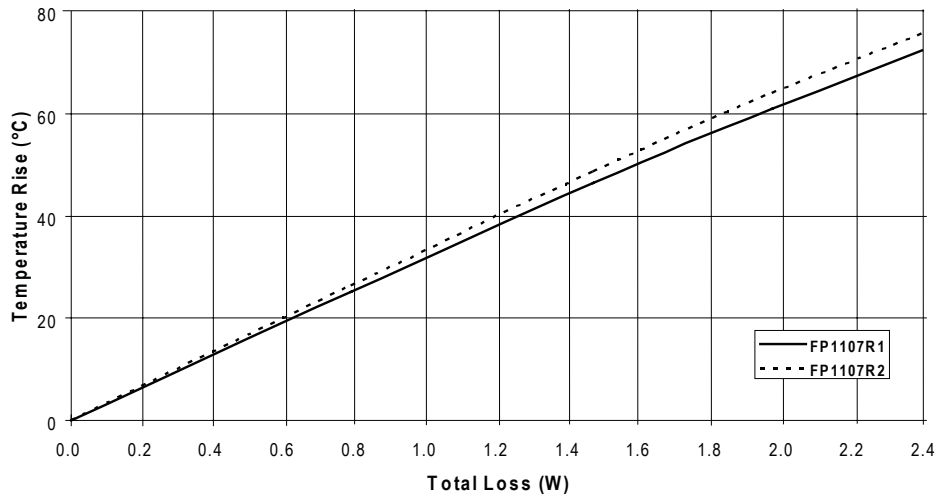


Part Marking: 1107Rx (Rx = DCR Indicator) Rxx = Inductance value in μH. (R = Decimal point) wwlyy = Date code R = Revision level

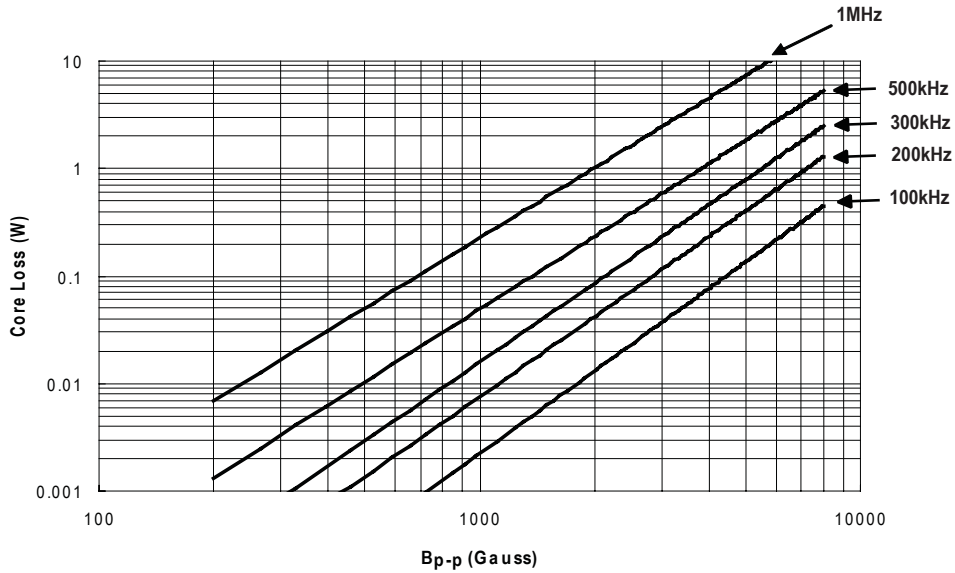
Packaging information - mm



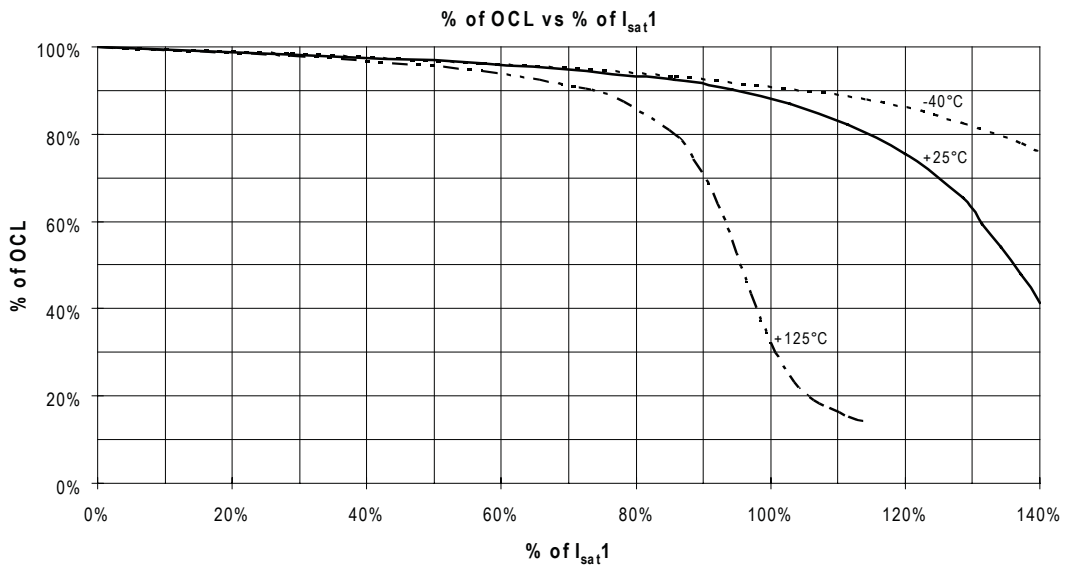
Temperature rise vs total loss



Core loss vs Bp-p



Inductance characteristics



Solder Reflow Profile

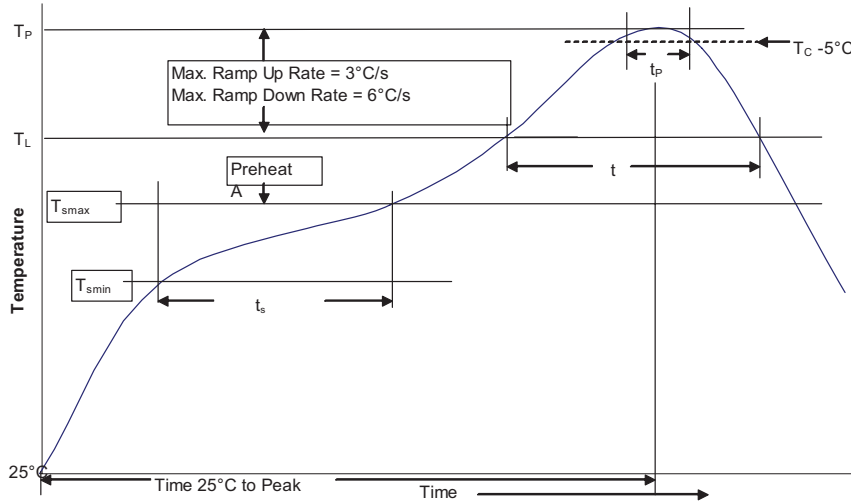


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm^3 <350	Volume mm^3 ≥ 350
<2.5mm	235°C	220°C
$\geq 2.5\text{mm}$	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	• Temperature min. (T_{smin})	100°C
	• Temperature max. (T_{smax})	150°C
	• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds
Average ramp up rate T_{smax} to T_P	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_P)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_P to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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